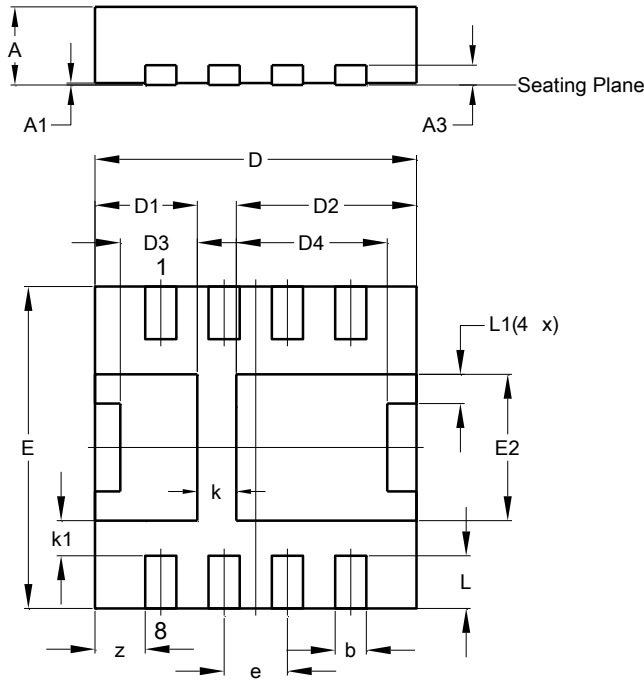


## Package Outline Dimensions

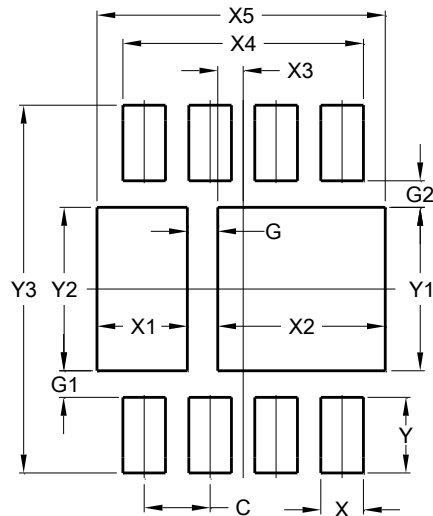
PowerDI3333-8 (Type F)



PowerDI3333-8 (Type F)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	--	--	0.203
b	0.27	0.37	0.32
D	3.25	3.35	3.30
D1	0.95	1.15	1.05
D2	1.75	1.95	1.85
D3	0.69	0.89	0.79
D4	1.45	1.65	1.55
E	3.25	3.35	3.30
E2	1.40	1.60	1.50
e	0.65BSC		
L	0.49	0.59	0.54
L1	0.20	0.40	0.30
z	--	--	0.515
k	--	--	0.40
k1	--	--	0.36
All Dimensions in mm			

## Suggested Pad Layout

PowerDI3333-8 (Type F)



Dimensions	Value (in mm)
C	0.650
G	0.300
G1	0.260
G2	0.260
X	0.420
X1	0.890
X2	1.650
X3	0.250
X4	2.370
X5	2.840
Y	0.740
Y1	1.600
Y2	1.600
Y3	3.600

### ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.